

L Number	Hits	Search Text	DB	Time stamp
60	10	("4493753" "4530740" "4780395" "4871623" "4894664" "4922265" "5194877" "5249358" "5443713" "5685491").PN.	USPAT	2004/05/09 18:38
61	7407	substrate with metal and photoresist and (microchannel or channel or hollow) and deposit\$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/05/09 18:40
63	13	substrate with metal and photoresist and (microchannel or channel or hollow) and deposit\$4 and coat\$4 and (build\$4 with wall)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/05/09 18:41
62	781	substrate with metal and photoresist and (microchannel or channel or hollow) and deposit\$4 and coat\$4 and build\$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/05/09 18:45
64	943	substrate and photoresist and (microchannel or channel or hollow) and (deposit\$4 with metal) and coat\$4 and build\$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/05/09 18:45
65	443	substrate and photoresist and (microchannel or channel or hollow) and (deposit\$4 with metal) and coat\$4 and build\$4 and wall	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/05/09 18:46
66	608	substrate and photoresist and (microchannel or channel or hollow) and (deposit\$4 with metal) and coat\$4 and build\$4 and wall\$2	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/05/09 18:53
67	9	"6136171"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/05/09 18:55
68	9	"6169394"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/05/09 18:55
69	6	("4059480" "4066491" "4276335" "4403234" "4413268" "4549188").PN.	USPAT	2004/05/09 19:05
70	28	4728392.URPN.	USPAT	2004/05/09 19:05
-	202	microneedle\$4 or (micro adj needle\$4)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/05/08 12:31
-	1	6177291.URPN.	USPAT	2002/10/30 11:33
-	14	("4604637" "5102832" "5110760" "5112773" "5204280" "5227322" "5240558" "5244828" "5244842" "5256587" "5308786" "5427974" "5427977" "5466626").PN.	USPAT	2002/10/30 11:34
-	4798	604/272,20,191,22,35,46,501,506,181,183,239 USPAT 191,186 2002/11/02 US-PGPUB; EPO; JPO; DERWENT; IBM TDB	USPAT	15:33
-	1953	604/272,20,191,22,35,46,501,506,181,183,239 USPAT 191,186 2002/10/31 and (needle or array)	US-PGPUB; EPO; JPO; DERWENT; IBM TDB	09:09

	2013	604/272,20,191,22,35,46,501,506,181,183,239 and (needle\$4 or array\$4)	US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT191,18	2002/10/31 09:09
	220	604/272,20,191,22,35,46,501,506,181,183,239 and needle\$4 and array\$4	US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT191,18	2002/10/31 09:13
	221	604/272,20,191,22,35,46,501,506,181,183,239 and \$8needle\$4 and array\$4	US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT191,18	2002/10/31 09:38
	0	291/890.01,890.1.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB;	2003/09/22 16:55
	1432	424/449,483.ccls.	EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB;	2003/09/22 16:56
	1179	216//75,100,102.ccls.	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT	2003/09/22 16:58
	35	("3964482" "4381963" "4784737" "5156591" "5162043" "5250023" "5256360" "5279544" "5318557" "5362307" "5498235" "5527288" "5551953" "5591139" "5611806" "5658515" "5681580" "5704520" "5711761" "5730714" "5735273" "5771890" "5800420" "5807375" "5814020" "5820622" "5827183" "5848985" "5848990" "5848991" "5855801" "6023629" "6038485" "6047208" "6129696").PN.	USPAT	2002/11/02 11:48
	723	29/890.01,890.1.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT;	2002/11/02 11:59
	25	29/890.01,890.1.ccls. and \$9needle\$2	US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT;	2002/11/02 13:11
	5	"6334856"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT	2002/11/02 13:11
	42	("2893392" "3034507" "3086530" "3123212" "3136314" "RE25637" "3221739" "3221740" "3556080" "3596660" "3675766" "3918449" "3964482" "4109655" "4159659" "4222392" "4771660" "4798582" "4921475" "4969468" "5054339" "5138220" "5250023" "5279544" "5279552" "5335670" "5364374" "5383512" "5401242" "5457041" "5527288" "5582184" "5591139" "5611806" "5611809" "5618295" "5658515" "5697901" "5801057" "5843114" "5879326" "6050988").PN.	USPAT	2002/11/02 13:14

	133	424/449, 483.ccls. and \$9needle\$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT	2002/11/02 14:38
	27	216//75, 100, 102.ccls. and \$9needle\$4		2002/11/02 14:38
	7	("3814097" "3964482" "5279543" "5279544" "5983136" "6219574" "6230051").PN.		2002/11/02 15:09
	7	("3814097" "3964482" "5279543" "5279544" "5983136" "6219574" "6230051").PN.	USPAT	2002/11/02 15:09
	515	604/272.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT;	2002/11/02 15:35
	956	Frazier.in.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT;	2002/11/02 15:36
	368	microneedle\$2	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT;	2002/11/02 16:04
	3	"6193700"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT;	2002/11/02 16:04
	147	(microneedle\$4 or (micro adj needle\$4)) and (substrate or support)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT;	2003/09/22 16:47
	10927	(printer or nozzle or ink) with substrate and support	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT;	2003/09/22 16:48
	755	printer with (nozzle or ink) with substrate and support	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT;	2003/09/22 16:48
	755	printer with (nozzle or ink) with substrate and support	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT;	2003/09/22 16:48
	257	printer with (nozzle or ink) with substrate and support and array	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT;	2003/09/22 16:50
	61	printer with (nozzle or ink) with substrate and support and array and etch	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT;	2003/09/22 16:50
	127	printer with (nozzle or ink) with substrate and support and array and etch\$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/09/22 16:50

	52	424/449,483.ccls. and array\$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT	2003/09/22 16:56
	123	216//75,100,102.ccls. and array\$4		2003/09/22 17:14
	6	("5406573" "5998298" "6145342" "6163638" "6291797" "6358854" "2001/0055831").PN.		2003/09/22 17:00
	15	216//75,100,102.ccls. and array\$4 and spacer\$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT	2003/09/22 17:14
	10990	(palladium or titanium or chromium or nickel or gold or copper) and substrate\$4 and (hollow or channel) and photoresist	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT	2004/05/06 14:39
	11598	(palladium or titanium or chromium or nickel or gold or copper) and (hollow or channel) and photoresist	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT	2004/05/06 08:49
	1478	(palladium or titanium or chromium or nickel or gold or copper) and substrate\$4 and (hollow or channel) and photoresist and electroplat\$7	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT	2004/05/06 14:59
	1253	(palladium or titanium or chromium or nickel or gold or copper) and substrate\$4 and (hollow or channel) and photoresist and electroplat\$7 and (support or interconnect\$8 or frame or foundation)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT	2004/05/06 08:51
	621	(palladium or titanium or chromium or nickel or gold or copper) and substrate\$4 and (hollow or channel) and photoresist and electroplat\$7 and (support or interconnect\$8 or frame or foundation) and array\$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT	2004/05/06 08:53
	559	(palladium or titanium or chromium or nickel or gold or copper) and substrate\$4 and (hollow or channel) and photoresist and electroplat\$7 and (support or interconnect\$8 or frame or foundation) and array\$4 and (point\$4 or tip\$4 or needle\$4 or jet\$4 or nozzle\$4)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT	2004/05/06 10:46
	7	5655665.URPN.		2004/05/06 09:04
	1008	(palladium or titanium or chromium or nickel or gold or copper) and substrate\$4 and (hollow or channel) and photoresist and electroplat\$7 and (support or interconnect\$8 or frame or foundation) and (point\$4 or tip\$4 or needle\$4 or jet\$4 or nozzle\$4)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/06 14:35
	8	("4285779" "4530740" "4707225" "4871623" "4894664" "4972204" "5199487" "5311896").PN.	USPAT	2004/05/06 11:17
	40	"5697901"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/06 14:38

	20	("3026874" "3288140" "3580254" "3814097" "4304866" "4767746" "4784737" "4788971" "4847193" "4868116" "4980286" "5036006" "5152757" "5225750" "5262128" "5364374" "5451513" "5457041" "5516670" "5523222").PN.	USPAT	2004/05/06 14:37
	26	"5807375"	USPAT; US_PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT;	2004/05/06 14:38
	1457	(palladium or titanium or chromium or nickel or gold or copper) and (ink\$4 or printer\$4) and (hollow or channel) and photoresist	US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT;	2004/05/06 14:40
	1251	(palladium or titanium or chromium or nickel or gold or copper) and (ink\$4 or printer\$4) and (hollow or channel) and photoresist and (array or dimension\$8)	USPAT; US_PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT;	2004/05/06 14:40
	1178	(palladium or titanium or chromium or nickel or gold or copper) and (ink\$4 or printer\$4) and (hollow or channel) and photoresist and (array or dimension\$8) and substrate	US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT;	2004/05/06 14:40
	238	(palladium or titanium or chromium or nickel or gold or copper) and (ink\$4 or printer\$4) and (hollow or channel) and photoresist and (array or dimension\$8) and substrate and electroplat\$4	US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT	2004/05/06 14:59
	18	("5252294" "5501893" "5569355" "5585069" "5632876" "5660728" "5681484" "5729244" "5755408" "5783452" "5801442" "5858193" "5863708" "5871158" "5876582" "5876675" "5897097" "5909280").PN.	USPAT	2004/05/06 14:47
	8	("3615913" "3895429" "5116495" "5128737" "5205902" "5298587" "5320875" "5575929").PN.	USPAT	2004/05/06 14:50
	16	5569355.URPN.	USPAT	2004/05/06 14:53
	9031	micromachine\$4 or micrchannel\$4	USPAT; US_PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT	2004/05/06 14:59
	4498	(palladium or titanium or chromium or nickel or gold or copper) and substrate\$4 and (micromachine\$4 or microchannel\$4)	US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT	2004/05/06 15:00
	1443	(palladium or titanium or chromium or nickel or gold or copper) and substrate\$4 and (micromachine\$4 or microchannel\$4) and photoresist	US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT	2004/05/06 15:00
	1203	(palladium or titanium or chromium or nickel or gold or copper) and substrate\$4 and (micromachine\$4 or microchannel\$4) and photoresist and (needle\$4 or tip\$4 or nozzle\$4 or point\$4)	US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT	2004/05/06 15:04
	1032	(palladium or titanium or chromium or nickel or gold or copper) and substrate\$4 and (micromachine\$4 or microchannel\$4) and photoresist and (needle\$4 or tip\$4 or nozzle\$4 or point\$4) and (channel\$4 or passage\$4 or hollow\$4 or flow\$4)	US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT	2004/05/06 15:45

-	10	("4221567" "4461304" "4478222" "4502938" "4874499" "4902278" "4969468" "5106365" "5130276" "5285131").PN.	USPAT	2004/05/06 15:32
-	23	5591139.URPN.	USPAT	2004/05/06 15:38
-	10	"6106751"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/05/06 15:45
-	0	"09787498"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/05/07 15:06
-	0	"09/787498"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/05/07 15:31
-	69	"4969468"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/05/07 15:43
-	3	5361760.URPN.	USPAT	2004/05/07 15:42
-	2	("4155353" "4969468").PN.	USPAT	2004/05/07 15:42
-	33	5457041.URPN.	USPAT	2004/05/07 15:43
-	350	microneedle\$4 or (micro adj needle\$4)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/05/08 09:37
-	656	microneedle\$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/05/08 09:37
-	321	microneedle\$4 and (hollow or channel\$4)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/05/08 10:01
-	15	5989445.URPN.	USPAT	2004/05/08 09:44
-	6	("3921916" "4455192" "5308442" "5385635" "5585827" "5588597").PN.	USPAT	2004/05/08 09:46
-	5	"5694901"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/05/08 10:01
-	40	"5697901"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/05/08 10:02
-	433	(palladium or titanium or chromium or nickel or gold or copper) and substrate\$4 and (micromachine\$4 or microchannel\$4) and photoresist and (needle\$4 or tip\$4 or nozzle\$4 or point\$4) and electropla\$8	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/05/08 12:53
-	5080	photoresist and (needle\$4 or tip\$4 or nozzle\$4 or point\$4) and electropla\$8	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/05/08 12:57

-	1032	photoresist and (needle\$4 or nozzle\$4) and electropla\$8	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/05/09 18:33
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